

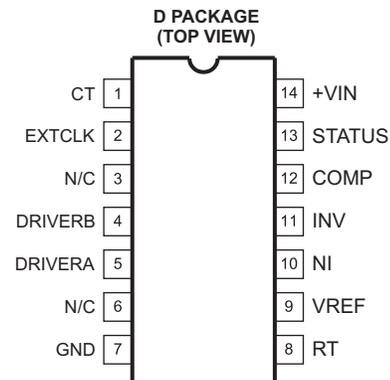
ISOLATED FEEDBACK GENERATOR

 Check for Samples: [UC2901-EP](#)

FEATURES

- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree ⁽¹⁾**
- **Amplitude-Modulation System for Transformer Coupling an Isolated Feedback Error Signal**
- **Low-Cost Alternative to Optical Couplers**
- **Internal 1% Reference and Error Amplifier**
- **Internal Carrier Oscillator Usable to 5 MHz**
- **Modulator Synchronizable to an External Clock**
- **Loop Status Monitor**

(1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



N/C = No internal connection

DESCRIPTION

The UC2901 is designed to solve many of the problems associated with closing a feedback control loop across a voltage isolation boundary. As a stable and reliable alternative to an optical coupler, UC2901 features an amplitude modulation system that allows a loop error signal to be coupled with a small RF transformer or capacitor.

The programmable, high-frequency oscillator within the UC2901 permits the use of smaller, less-expensive transformers, which can readily be built to meet the isolation requirements of today's line-operated power systems. As an alternative to RF operation, the external clock input to these devices allows synchronization to a system clock or to the switching frequency of an SMPS.

An additional feature is a status monitoring circuit that provides an active low output when the sensed error voltage is within $\pm 10\%$ of the reference. The DRIVERA output, DRIVERB output, and STATUS output are disabled until the input supply has reached a sufficient level to allow proper operation of the device.

Because these devices also can be used as a DC driver for optical couplers, the benefits of 4.5 V to 40 V supply operation, a 1% accurate reference, and a high-gain general-purpose amplifier offer advantages, even though an AC system may not be desired.

ORDERING INFORMATION

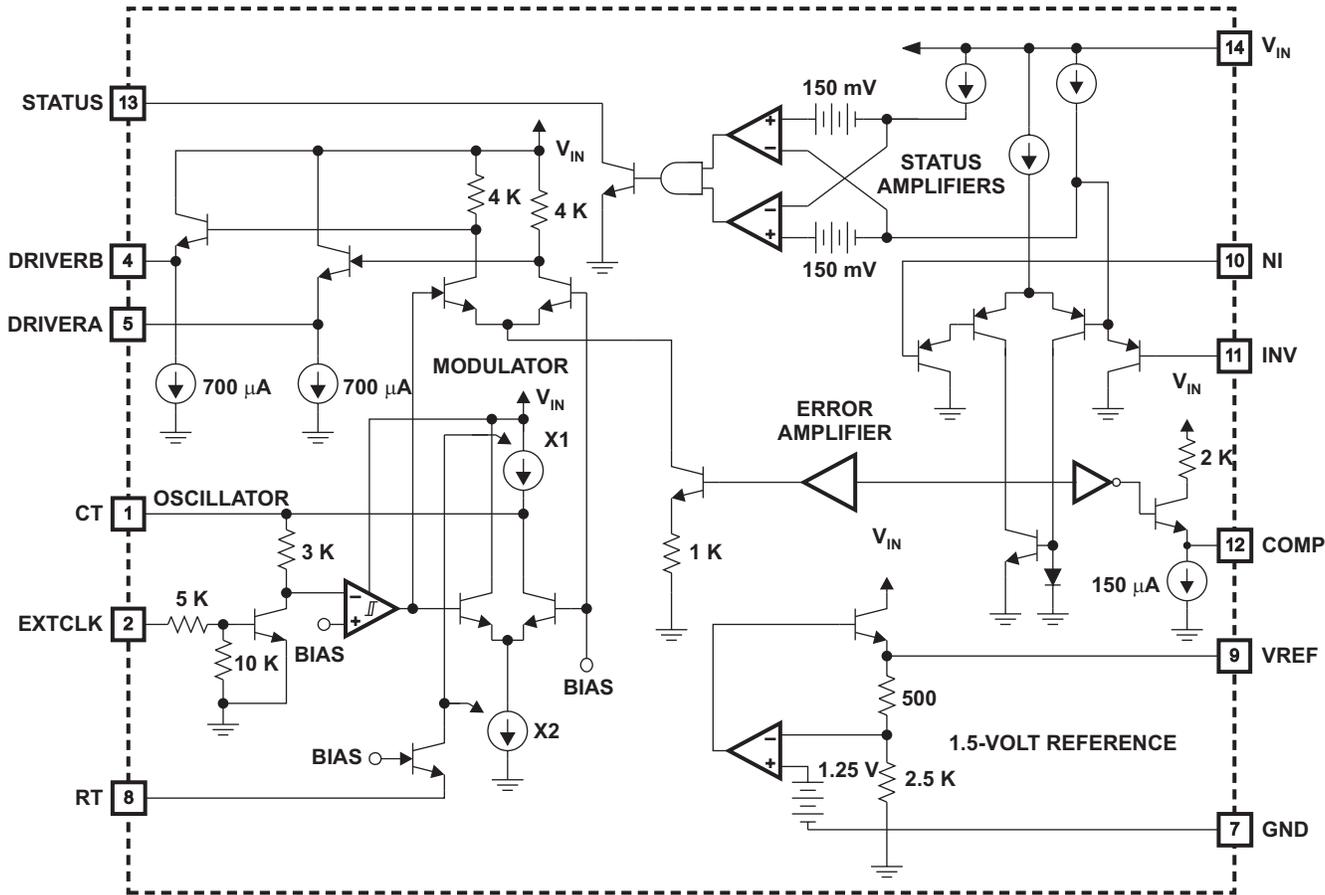
T _A	PACKAGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	D (SOIC)	UC2901MDREP	UC2901MEP

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

UC2901 SIMPLIFIED SCHEMATIC



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{IN}	Input supply voltage		40	V
	Reference output current		-10	mA
	Driver output current		-35	mA
	Status indicator voltage		40	V
	Status indicator current		20	mA
	External clock input		40	V
	Error amplifier inputs	-0.5	35	V
	Power dissipation at $T_A = 25^\circ\text{C}$		1000	mW
	Operating junction temperature range	-55	150	$^\circ\text{C}$
	Storage temperature range ⁽²⁾	-65	150	$^\circ\text{C}$
	Lead temperature (soldering, 10 seconds)		300	$^\circ\text{C}$

(1) Voltages are referenced to ground, pin 7. Currents are positive into, and negative out of the specified terminal.

(2) Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

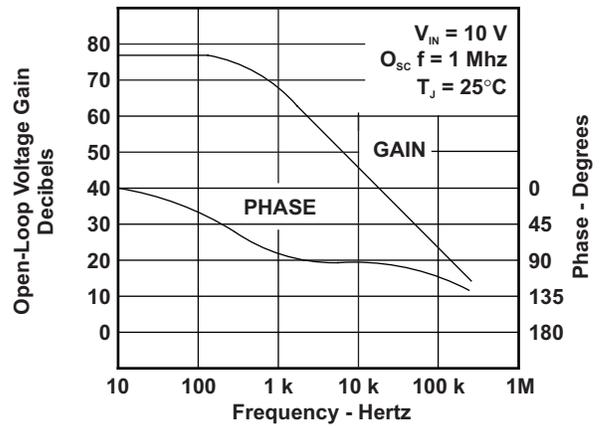
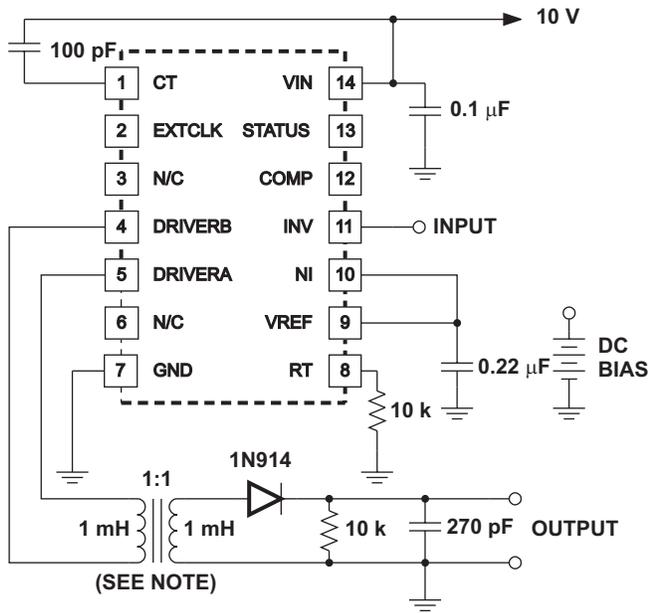
DISSIPATION RATING TABLE - FREE-AIR TEMPERATURE

PACKAGE	AIR FLOW (CFM)	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
D	0	1000 mW	8 mW/°C	630 mW	510 mW	180 mW

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Reference Section					
Output voltage	T _A = 25°C	1.485	1.5	1.515	V
	T _{MIN} ≤ T _A ≤ T _{MAX}	1.470	1.5	1.530	
Line regulation	V _{IN} = 4.5 to 35 V		2	10	mV
Load regulation	I _{OUT} = 0 to 5 mA		4	10	mV
Short-circuit current	T _A = 25°C		-35	-55	mA
Error Amplifier Section (To Compensation Terminal)					
Input offset voltage	V _{CM} = 1.5 V		1	4	mV
Input bias current	V _{CM} = 1.5 V		-1	-3	μA
Input offset current	V _{CM} = 1.5 V		0.1	1	μA
Small-signal open-loop gain		40	60		dB
CMRR	V _{CM} = 0.5 V to 7.5 V	60	80		dB
PSRR	V _{IN} = 5 V to 25 V	80	100		dB
Output swing, ΔV _O		0.4	0.7		V
Maximum sink current		90	150		μA
Maximum source current		-2	-3		mA
Gain bandwidth product			1		MHz
Slew rate			0.3		V/μs
Modulators/Drivers Section (From Compensation Terminal)					
Voltage gain		11	12	13	dB
Output swing		±1.6	±2.8		V
Driver sink current		500	700		μA
Driver source current		-15	-35		mA
Gain bandwidth product			25		MHz
Oscillator Section					
Initial accuracy	T _A = 25°C	140	150	160	kHz
	T _{MIN} ≤ T _A ≤ T _{MAX}	130		170	
Line sensitivity	V _{IN} = 5 V to 35 V		0.15	0.35	%/V
Maximum frequency	R _T = 10 K, C _T = 10 pF		5		MHz
External clock low threshold	Pin 1 (C _T) = V _{IN}	0.5			V
External clock high threshold	Pin 1 (C _T) = V _{IN}			1.6	V
Status Indicator Section					
Input voltage window	At E/A inputs, V _{CM} = 1.5 V	±135	±150	±165	mV
Saturation voltage	E/A Δinput = 0 V, I _{SINK} = 1.6 mA			0.45	V
Maximum output current	Pin 13 = 3 V, E/A Δ input = 0 V	8	15		mA
Leakage current	Pin 13 = 40 V, E/A Δ input = 0.2 V		0.05	1	μA
Supply current	V _{IN} = 35 V		5	8	mA
UVLO Section					
Drivers-enabled threshold	At input supply V _{IN}		3.9	4.5	V
Status output-enabled threshold	At input supply V _{IN}		3.9	4.5	V
Change in reference output	When V _{IN} reaches UVLO threshold		-2	-30	mV



Note: Transformer Data: N1 = N2 = 20 TAWG 26
Core = Ferroxcube 3E2A Ferrite, 0.5" O.D. Toroid
Carrier Frequency = 1 Mhz

Figure 1. Transformer-Coupled Open-Loop Transfer Function

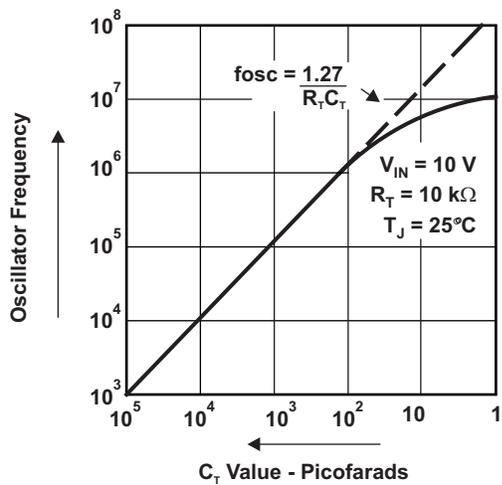


Figure 2. Oscillator Frequency

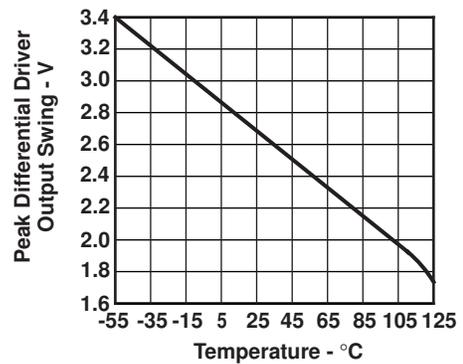


Figure 3. Typical Driver Output Swing vs Temperature

APPLICATION INFORMATION

The error amplifier compensation terminal, pin 12, is intended as a source of feedback to the amplifier's inverting input at pin 11. For most applications, a series DC blocking capacitor should be part of the feedback network. The amplifier is compensated internally for unity feedback.

The waveform at the driver outputs is a squarewave, with an amplitude that is proportional to the error amplifier input signal. There is a fixed 12 dB of gain from the error amplifier compensation pin to the modulator driver outputs. The frequency of the output waveform is controlled by either the internal oscillator or an external clock signal.

With the internal oscillator, the squarewave has a fixed 50% duty cycle. If the internal oscillator is disabled by connecting pin 1, C_R , to V_{IN} , then the frequency and duty cycle of the output is determined by the input clock waveform at pin 2. If the oscillator remains disabled, and there is not clock input at pin 2, there will be a linear 12-dB signal gain to one or the other of the driver outputs, depending on the DC state of pin 2.

The driver outputs are emitter followers that source a minimum of 15 mA of current. The sink current, internally limited at 700 mA, can be increased by adding resistors to ground at the driver outputs.

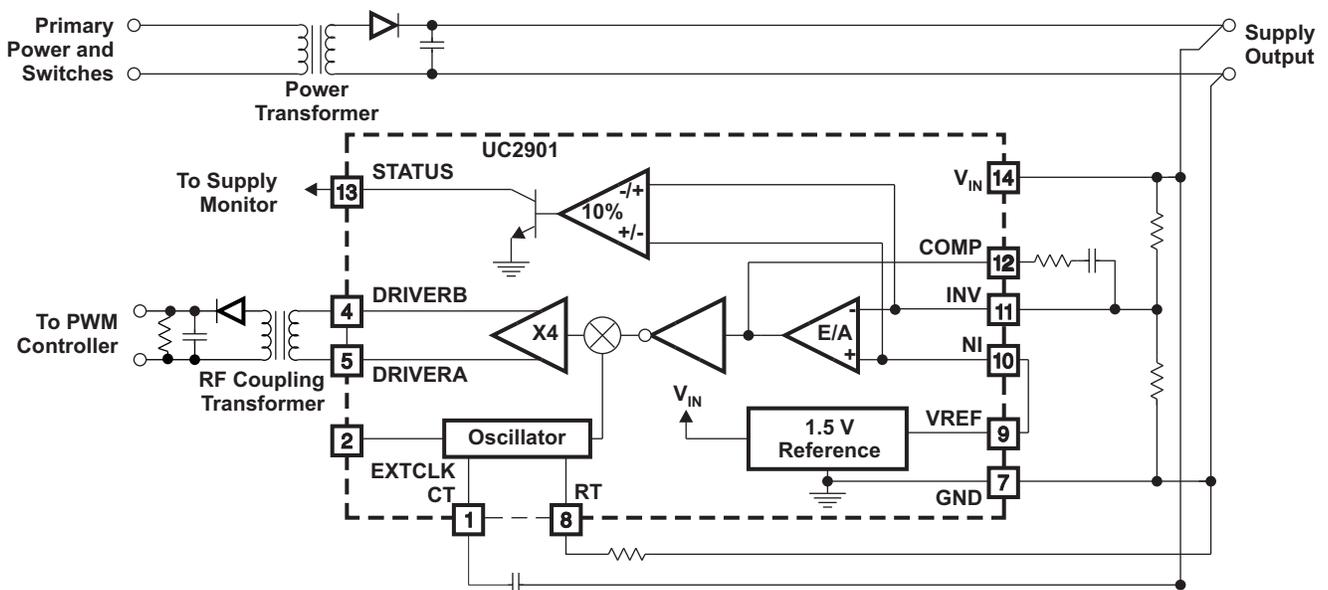


Figure 4. Transformer-Coupled Feedback

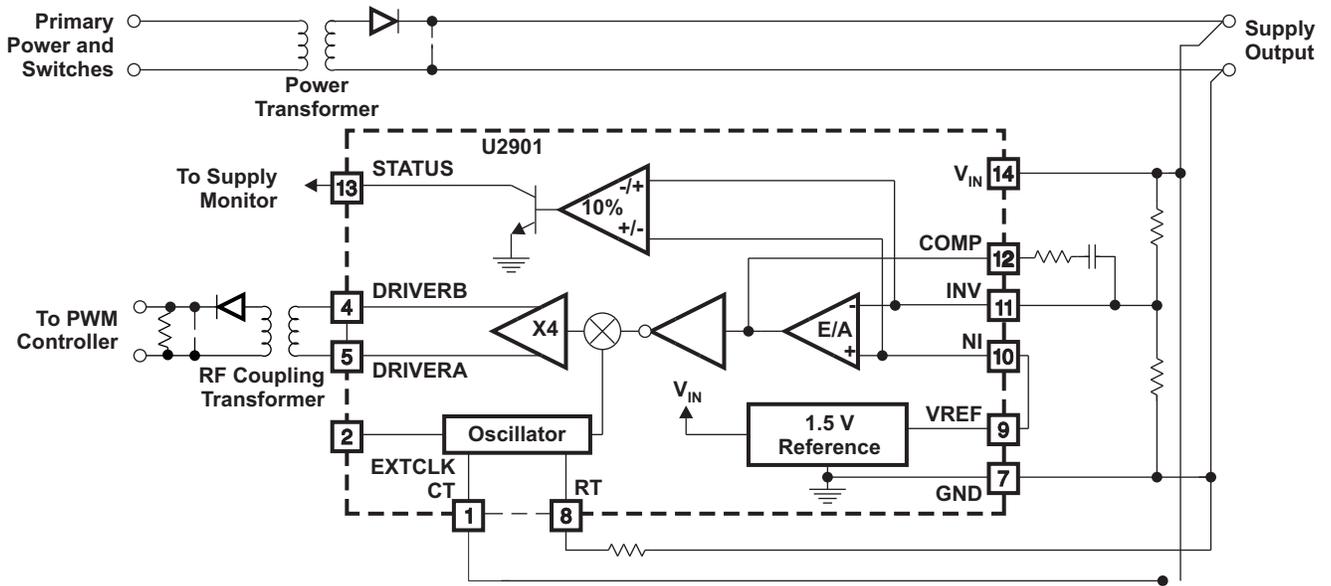


Figure 5. Feedback-Coupled at Switching Frequency

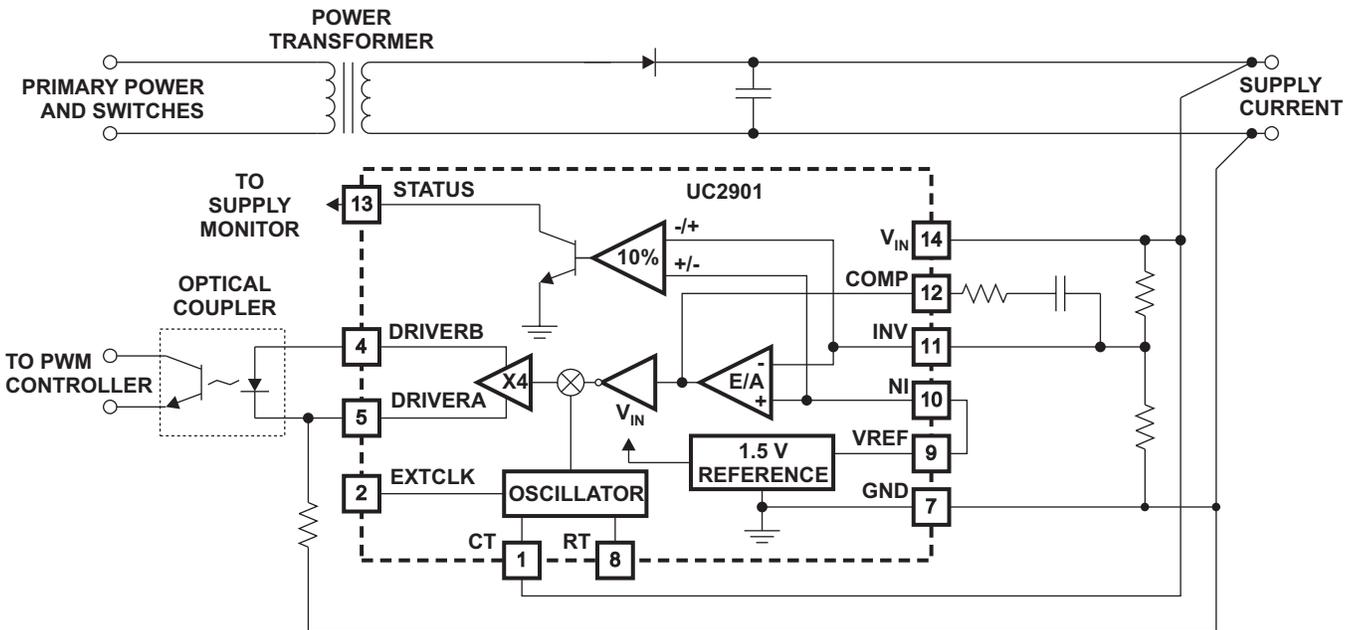


Figure 6. Optically-Coupled DC Feedback

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
UC2901MDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	UC2901MEP	Samples
UC2901MDREPG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	UC2901MEP	Samples
V62/07609-01XE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	UC2901MEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

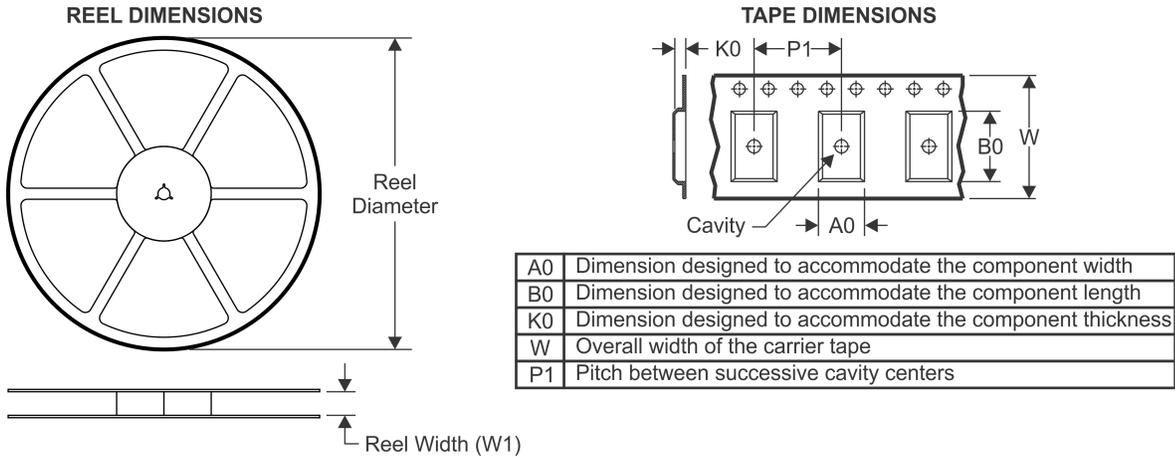
OTHER QUALIFIED VERSIONS OF UC2901-EP :

- Catalog: [UC2901](#)

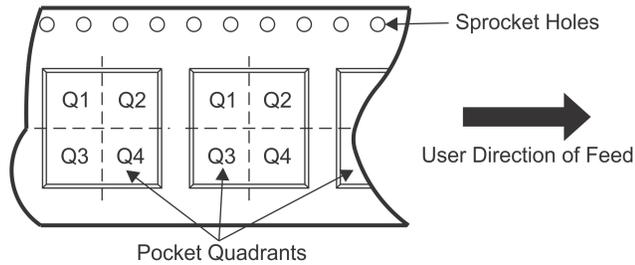
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2901MDREP	SOIC	D	14	2500	330.0	16.4	6.55	9.05	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

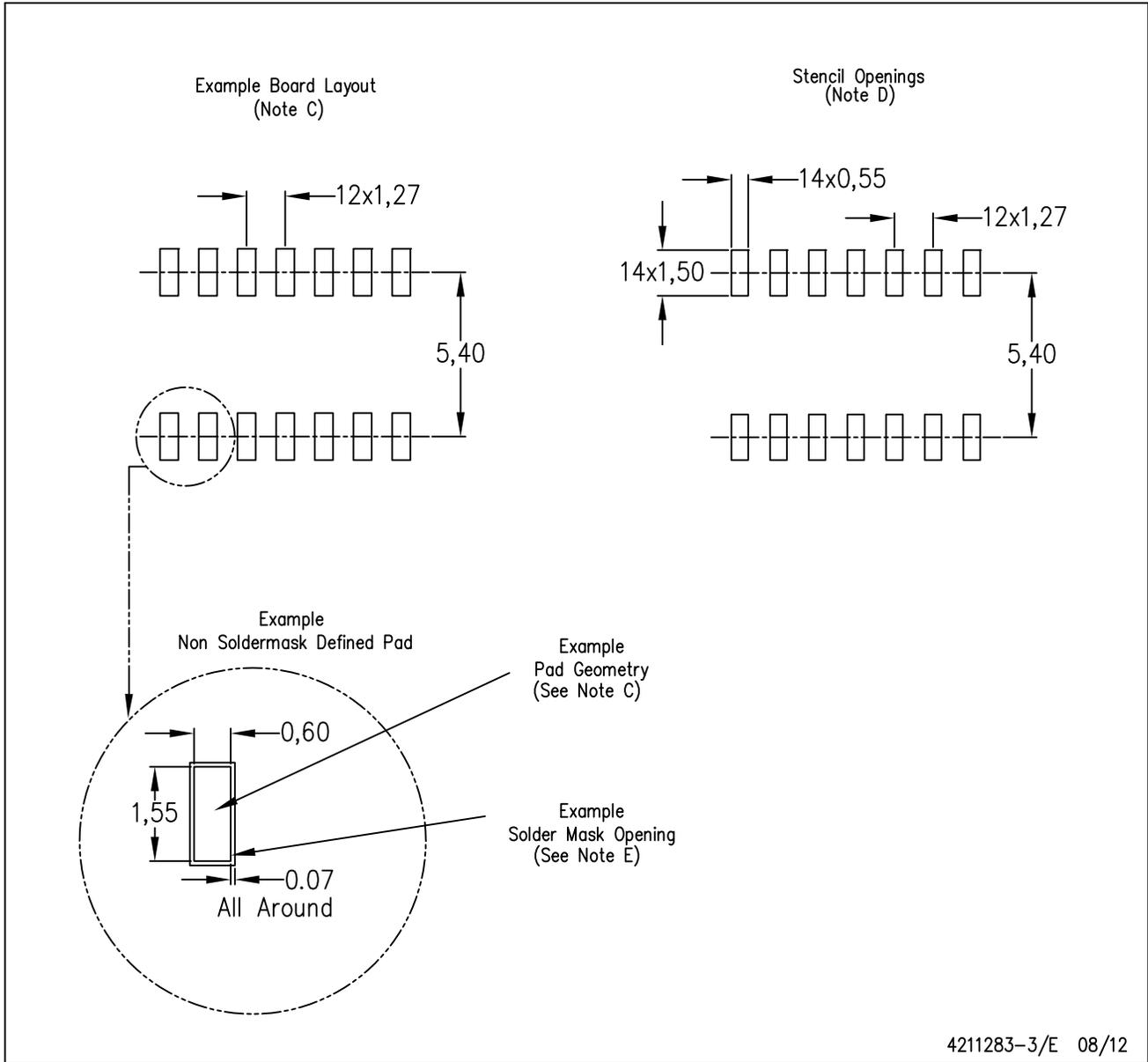


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2901MDREP	SOIC	D	14	2500	346.0	346.0	33.0

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.